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Vishay Semiconductors

## High Speed Infrared Emitting Diodes, 940 nm, **Surface Emitter Technology**

### VSMY2941RGX01







#### **DESCRIPTION**

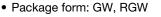
As part of the SurfLight<sup>TM</sup> portfolio, the VSMY2941X01 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### **APPLICATIONS**

- · Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors

### **FEATURES**

· Package type: surface-mount



Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8

• Peak wavelength:  $\lambda_p = 940 \text{ nm}$ 

- AEC-Q101 qualified
- High radiant power
- · Very high radiant intensity
- Angle of half intensity: φ = ± 8°
- · Terminal configurations: gullwing or reverse gullwing



• Floor life: 4 weeks, MSL 2a, according to J-STD-020

• Material categorization: for definitions of compliance











- - please see www.vishay.com/doc?99912

PRODUCT SUMMARY					
COMPONENT	I <sub>e</sub> (mW/sr)	φ (deg)	$\lambda_{\mathbf{P}}$ (nm)	t <sub>r</sub> (ns)	
VSMY2941RGX01	160	± 8	940	5	
VSMY2941GX01	160	± 8	940	5	

### Note

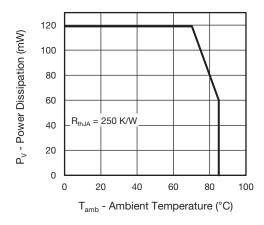
Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY2941RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMY2941GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

· MOQ: minimum order quantity

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_{R}$	5	V
Forward current		I <sub>F</sub>	70	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I <sub>FM</sub>	140	mA
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	500	mA
Power dissipation		P <sub>V</sub>	120	mW
Junction temperature		Tj	100	°C
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C
Soldering temperature	According to Fig. 10, J-STD-020	T <sub>sd</sub>	260	°C
Thermal resistance junction-to-ambient	J-STD-051, soldered on PCB	R <sub>thJA</sub>	250	K/W







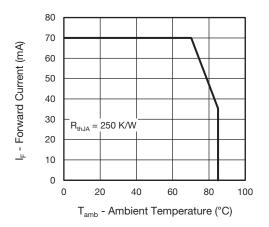


Fig. 2 - Forward Current Limit vs. Ambient Temperature

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
	$I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$	$V_{F}$	_	1.4	1.7	V
Forward voltage	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	V <sub>F</sub>	-	1.5	-	V
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	$V_{F}$	-	2.6	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 50 mA	TK <sub>VF</sub>	_	-0.7	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation		μΑ	
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	30	-	pF
	$I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$	l <sub>e</sub>	60	115	170	mW/sr
Radiant intensity	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	l <sub>e</sub>	-	160	-	mW/sr
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	l <sub>e</sub>	=	850	-	mW/sr
Radiant power	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	φ <sub>e</sub>	-	40	-	mW
Temperature coefficient of radiant power	I <sub>F</sub> = 50 mA	TΚφ <sub>e</sub>	=	-0.2	-	%/K
Angle of half intensity		φ	=	± 8	-	deg
Peak wavelength	I <sub>F</sub> = 50 mA	$\lambda_{p}$	920	940	960	nm
Spectral bandwidth	I <sub>F</sub> = 70 mA	Δλ	=	55	-	nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 70 mA	TKλ <sub>p</sub>	-	0.28	-	nm/K
Rise time	I <sub>F</sub> = 70 mA, 10 % to 90 %	t <sub>r</sub>	-	5	-	ns
Fall time	I <sub>F</sub> = 70 mA, 10 % to 90 %	t <sub>f</sub>	ı	6	-	ns

### **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

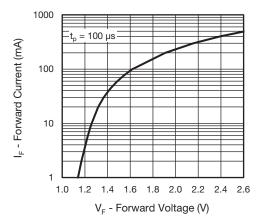


Fig. 3 - Forward Current vs. Forward Voltage

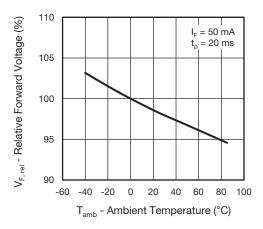


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

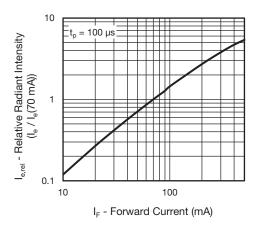


Fig. 5 - Radiant Intensity vs. Forward Current

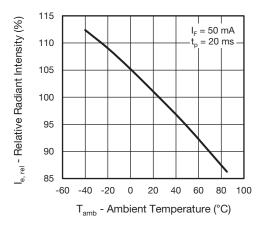


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

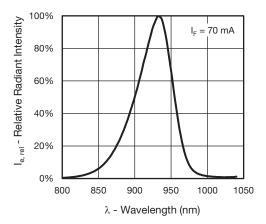


Fig. 7 - Relative Radiant Intensity vs. Wavelength

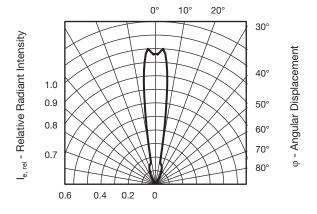


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

### **SOLDER PROFILE**

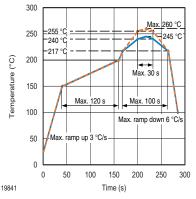


Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

Drawing-No.: 6.544-5391.03-4

Issue: 2; 19.09.14

### **DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

#### **FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

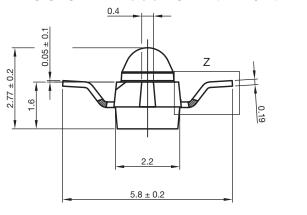
Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

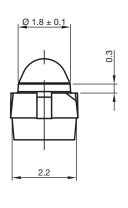
Moisture sensitivity level 2a, according to J-STD-020.

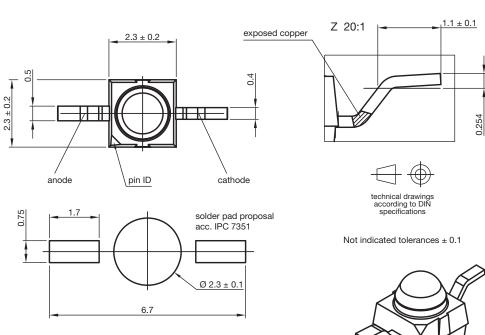
### **DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40  $^{\circ}$ C (+ 5  $^{\circ}$ C), RH < 5  $^{\circ}$ M.

### PACKAGE DIMENSIONS in millimeters: VSMY2941RGX01

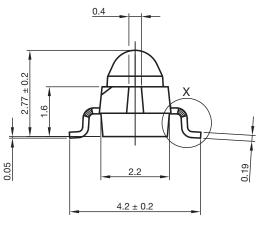


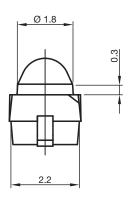


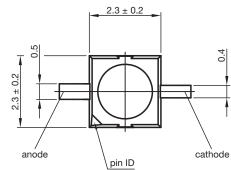


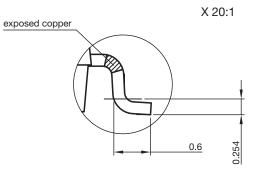
Rev. 1.0, 08-Nov-17 **4** Document Number: 84573

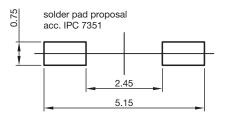
### PACKAGE DIMENSIONS in millimeters: VSMY2941GX01





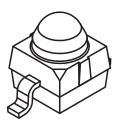








Not indicated tolerances ± 0.1



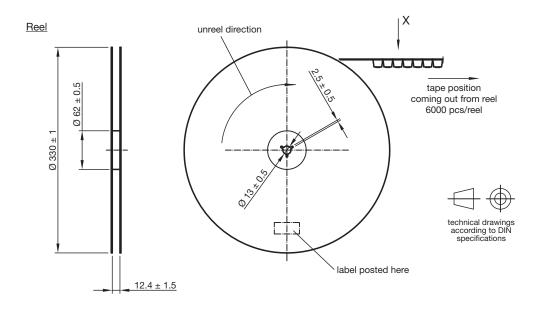
Drawing-No.: 6.544-5383.03-4

Issue: 2; 19.09.14

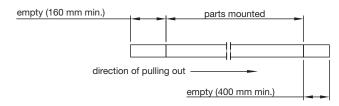
 $1.75 \pm 0.1$ 

 $4 \pm 0.1$ 

### TAPING AND REEL DIMENSIONS in millimeters: VSMY2941RGX01



#### Leader and trailer tape



### Terminal position in tape

Device	Lead I	Lead II	
VEMT2000	Collector	Emitter	
VEMT2500	Collector	Ellitter	
VEMD2000			
VEMD2500			
VSMB2000	Cathode	Anode	
VSMG2000			
VSMF2890RG			
VSMY2850RG	Anode	Cathode	
VSMY2940RG	Anoue	Califode	

3.05 ± 0.1

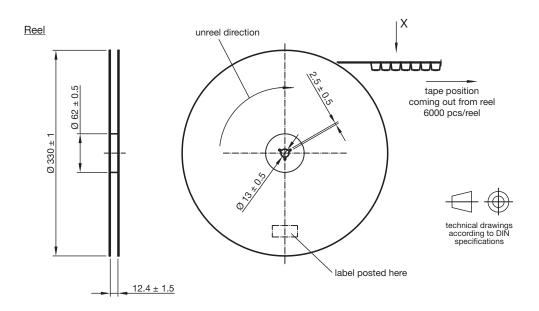
II

Ø 1.55 ± 0.05

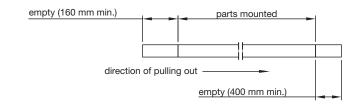
Drawing-No.: 9.800-5100.01-4

Issue: 4; 19.09.14

### TAPING AND REEL DIMENSIONS in millimeters: VSMY2941GX01

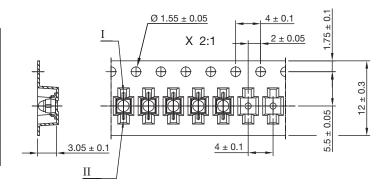


#### Leader and trailer tape



### Terminal position in tape

Lead I	Lead II	
Cathode	Anode	
Collector	Emitter	
Collector	Emiller	
Anada	Cathode	
Alloue	Callioue	



Drawing-No.: 9.800-5091.01-4

Issue: 5; 19.09.14



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